NUR460

Ultrafast power diode Rev. 2 — 20 July 2011

Product data sheet

Product profile 1.

1.1 General description

Ultrafast epitaxial power diode in a SOD141 (DO-201AD) axial lead plastic package.

1.2 Features and benefits

- Axial leaded plastic package
- Fast switching
- High voltage capability

- Low forward voltage drop
- Low thermal resistance
- Soft recovery characteristic

1.3 Applications

■ Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

■ High frequency switched-mode power supplies

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	-	600	V
I _{F(AV)}	average forward current	square-wave pulse; $\delta = 0.5$; see <u>Figure 1</u> ; see <u>Figure 2</u>	-	-	4	Α
Static char	racteristics					
V _F	forward voltage	$I_F = 4 \text{ A}$; $T_j = 25 \text{ °C}$; see <u>Figure 4</u>	-	-	1.28	V
Dynamic c	haracteristics					
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}$; $V_R = 30 \text{ V}$; $dI_F/dt = 50 \text{ A/µs}$; $T_j = 25 \text{ °C}$; Ramp Recovery; see Figure 5	-	33	65	ns
		$\begin{split} I_R &= 1 \text{ A; } I_F = 0.5 \text{ A;} \\ I_{R(meas)} &= 0.25 \text{ A; } T_j = 25 \text{ °C;} \\ \text{Step Recovery; see } \underline{\text{Figure 6}} \end{split}$	-	25	50	ns



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2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		v 14 .
2	Α	anode	k a	K
			SOD141 (DO-201AD)	

3. Ordering information

Table 3. Ordering information

Type number	Package				
	Name	Description	Version		
NUR460	DO-201AD	Hermetically sealed plastic package; axial leaded; 2 leads	SOD141		

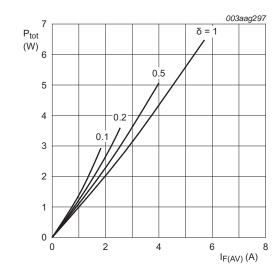
4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

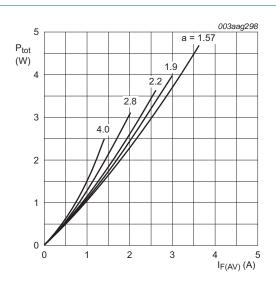
Symbol	Parameter	Conditions	Min	Max	Unit
V_{RRM}	repetitive peak reverse voltage		-	600	V
V_{RWM}	crest working reverse voltage		-	600	V
V _R	reverse voltage	DC	-	600	V
I _{F(AV)}	average forward current	square-wave pulse; $\bar{\delta}$ = 0.5; see <u>Figure 1</u> ; see <u>Figure 2</u>	-	4	Α
I _{FRM}	repetitive peak forward current	square-wave pulse; $\delta = 0.5$	-	8	А
I _{FSM}	non-repetitive peak forward current	t_p = 8.3 ms; sine-wave pulse; $T_{j(init)}$ = 25 °C; see <u>Figure 3</u>	-	110	Α
		t_p = 10 ms; sine-wave pulse; $T_{j(init)}$ = 25 °C; see <u>Figure 3</u>	-	100	Α
T _{stg}	storage temperature		-40	150	°C
Tj	junction temperature		-	150	°C

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$$\begin{split} I_{\textit{F(AV)}} = & I_{\textit{F(RMS)}} \times \sqrt{\pmb{\delta}} \\ V_{\text{O}} = & 0.968 \text{ V; R}_{\text{S}} = 0.036 \Omega \end{split}$$

Fig 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor =
$$I_{F(RMS)}/I_{F(AV)}$$

 $V_{O} = 0.968V$; $R_{s} = 0.036\Omega$

Fig 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

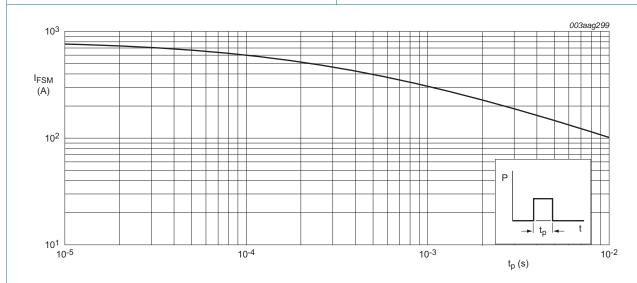


Fig 3. Non-repetitive peak forward current as a function of pulse width; square waveform; maximum values

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5. Thermal characteristics

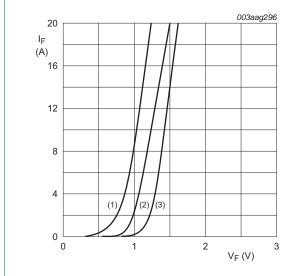
Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	-	55	-	K/W

6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static cha	racteristics					
V _F	forward voltage	$I_F = 4 \text{ A}$; $T_j = 25 \text{ °C}$; see Figure 4	-	-	1.28	V
		$I_F = 4 \text{ A}; T_j = 150 \text{ °C}; \text{ see } \frac{\text{Figure 4}}{\text{Minimum 1}}$	-	0.88	1.05	V
I _R	reverse current	$V_R = 600 \text{ V}; T_j = 25 ^{\circ}\text{C}$	-	-	50	μΑ
Dynamic	characteristics					
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}$; $V_R = 30 \text{ V}$; $dI_F/dt = 50 \text{ A/}\mu\text{s}$; Ramp Recovery; T_j 25 °C; see Figure 5	-	33	65	ns
		$I_F = 0.5 \text{ A}$; $I_R = 1 \text{ A}$; Step Recovery; $I_{R(meas)} = 0.25 \text{ A}$; $T_j = 25 ^{\circ}\text{C}$; see Figure 6	-	25	50	ns



 $V_{o} = 0.968 \text{ V}; R_{s} = 0.036\Omega;$

(1) $T_j = 150$ °C; typical value;

(2) $T_j = 150$ °C; maximum value;

(3) $T_i = 25$ °C; maximum value

Fig 4. Forward current as a function of forward voltage

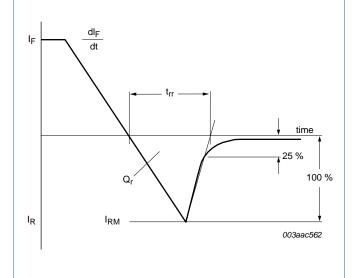
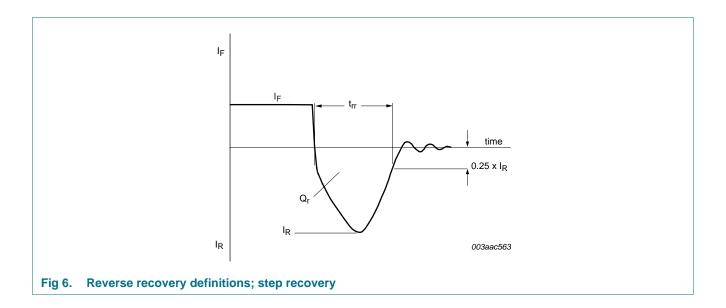


Fig 5. Reverse recovery definitions; ramp recovery

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7. Package outline

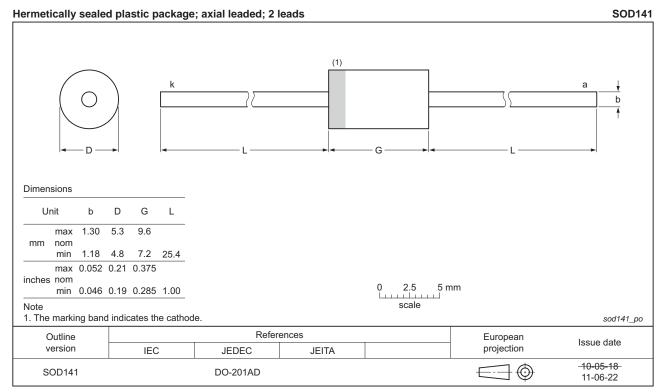


Fig 7. Package outline SOD141 (DO-201AD)

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8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
NUR460 v.2	20110720	Product data sheet	-	NUR460 v.1
Modifications:	 Various chang 			
NUR460 v.1	20110704	Product data sheet	-	-

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9. Legal information

9.1 Data sheet status

Document status [1] [2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Address:

401 Building No.5, JiuGe Business Center, Lane 2301, Yishan Rd Minhang District, Shanghai , China

> Sales:

Direct +86 (21) 6401-6692

Email amall@ameya360.com

QQ 800077892

Skype ameyasales1 ameyasales2

Customer Service :

Email service@ameya360.com

Partnership :

Tel +86 (21) 64016692-8333

Email mkt@ameya360.com